

WHAT IS CLAIMED IS:

1. An integrated circuit mounting structure comprising:  
an integrated circuit;  
electrodes formed on a lower surface of said integrated circuit;  
pieces of conductive material attached to said electrodes, respectively;  
a substrate;  
terminals provided on portions facing said pieces of conductive material,  
respectively, on an upper surface of said substrate; and  
connection members for connecting the terminals to said pieces of conductive  
material, respectively.
2. The integrated circuit mounting structure as claimed in claim 1, wherein said  
pieces of conductive material have an even thickness.
3. The integrated circuit mounting structure as claimed in claim 1, wherein said  
pieces of conductive material are copper plated with gold.
4. An integrated circuit mounting structure comprising:  
an integrated circuit;  
an electrode formed on an upper surface of the integrated circuit;  
a substrate;  
a lead provided on said substrate, one end of said lead is connected to said  
electrode; and  
a concave portion formed at the portion of the lead adjacent to said electrode,  
the thickness of said concave portion is thinner than a non-concave portion of the lead.

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5. The integrated circuit mounting structure claimed in claim 4, wherein the length from a tip of said lead to the edge of said concave portion is equal to or similar to the length of a side of said electrode on said integrated circuit.

6. The integrated circuit mounting structure claimed in claim 4, wherein the thickness of said concave portion is formed so that said lead can be cut at said concave portion when a tensile force is applied to said lead.

7. An integrated circuit mounting method for mounting an integrated circuit on a first substrate, comprising the steps of:

connecting one end of a lead provided on a second substrate to an electrode of said integrated circuit;

cutting the lead of said substrate so that a piece of said lead can be left on said electrode; and

connecting the piece left on the electrode of said integrated circuit to a terminal on said first substrate.

8. The integrated circuit mounting method as claimed in claim 7, further comprising the step of:

decreasing the thickness of a portion of said lead adjacent to the electrode of said integrated circuit compared to a portion of said lead not adjacent to the electrode.

9. The integrated circuit mounting method as claimed in claim 8, wherein the lead is cut during said cutting step at a portion that had been decreased by said decreasing step.

10. The integrated circuit mounting method as claimed in claim 7, further comprising the step of decreasing the thickness of the portion of said lead adjacent to the electrode of said integrated circuit by etching compared to a portion of said lead not adjacent to the electrode.

11. The integrated circuit mounting method as claimed in claim 7, wherein said step of cutting cuts the portion of said lead adjacent to the electrode of said integrated circuit.

12. An integrated circuit mounting method for mounting an integrated circuit on a mounting substrate, comprising the steps of:

connecting one end of a lead provided on a substrate to an electrode of said integrated circuit;

inspecting said integrated circuit by using the lead on said substrate;

cutting the lead on said substrate so that a piece of said lead could be left on said electrode; and

connecting the piece left on said electrode of said integrated circuit to a terminal of said mounting substrate.

13. The integrated circuit mounting method as claimed in claim 12, further comprising the step of:

decreasing the thickness of the portion of said lead adjacent to the electrode of said integrated circuit compared to a portion of said lead not adjacent to the electrode.

14. The integrated circuit mounting method as claimed in claim 13, wherein the lead is cut during said cutting step at a portion that had been decreased by said decreasing step.

15. The integrated circuit mounting method as claimed in claim 12, further comprising the step of decreasing the thickness of the portion of said lead adjacent to the electrode of said integrated circuit by etching compared to a portion of said lead not adjacent to the electrode.

16. The integrated circuit mounting method as claimed in claim 12, wherein said step of cutting cuts the portion of said lead adjacent to the electrode of said integrated circuit.

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